

Schottky Barrier Diode

CMS30I40A

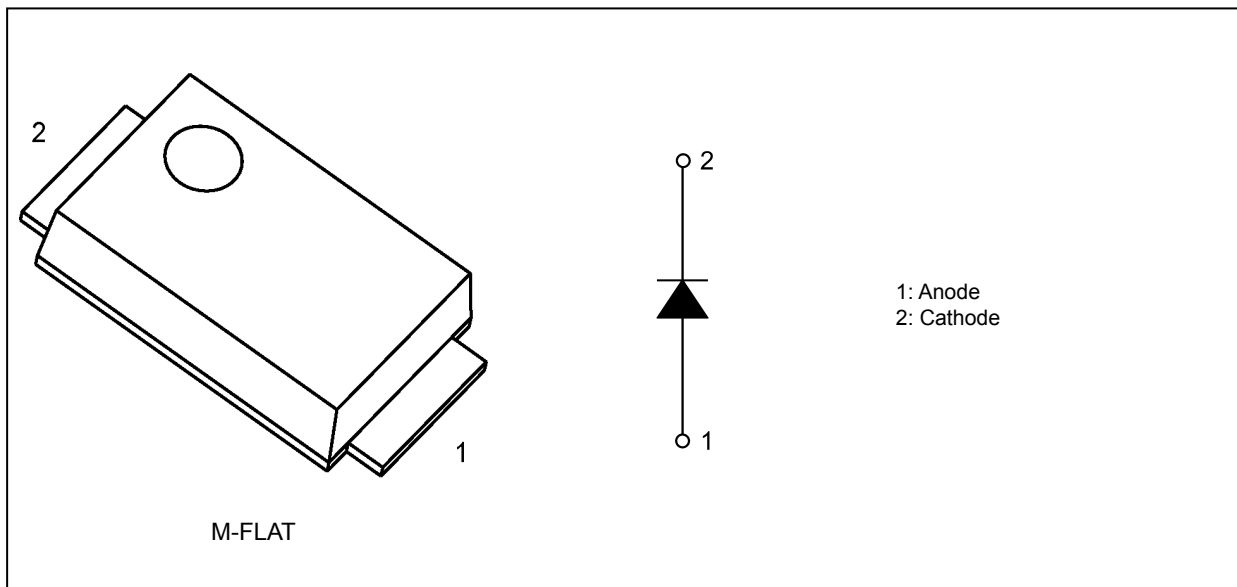
1. Applications

- Secondary Rectification in Switching Regulators
- Reverse-Current Protection in Mobile Devices

2. Features

- (1) Peak forward voltage: $V_{FM} = 0.55 \text{ V (max)@} I_{FM} = 3.0 \text{ A}$
- (2) Average forward current: $I_{F(AV)} = 3.0 \text{ A}$
- (3) Repetitive peak reverse voltage: $V_{RRM} = 40 \text{ V}$
- (4) Small, thin package suitable for high-density board assembly
Toshiba Nickname: M-FLAT™

3. Packaging and Internal Circuit Pin Assignment



Start of commercial production
2010-10

4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Note	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	—	40	V
Average forward current	$I_{F(AV)}$	(Note 1)	3.0	A
Non-repetitive peak forward surge current	I_{FSM}	(Note 2)	25	
Junction temperature	T_j	—	150	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 1: $T_l = 103^\circ\text{C}$, square wave ($\alpha = 180^\circ$), $V_R = 20\text{ V}$

Note 2: $f = 50\text{ Hz}$, half-sine wave

5. Thermal Characteristics

Characteristics	Symbol	Note	Test Condition	Max	Unit
Thermal resistance (junction-to-ambient)	$R_{th(j-a)}$	—	Device mounted on a ceramic board (soldering land size: 2 mm × 2 mm)	60	$^\circ\text{C/W}$
		—	Device mounted on a glass-epoxy board (soldering land size: 6 mm × 6 mm)	135	
Thermal resistance (junction-to-lead)	$R_{th(j-l)}$	—	Junction to cathode lead	16	

6. Electrical Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	$V_{FM(1)}$	—	$I_{FM} = 0.5\text{ A}$ (pulse measurement)	—	0.32	—	V
	$V_{FM(2)}$	—	$I_{FM} = 1.0\text{ A}$ (pulse measurement)	—	0.37	—	
	$V_{FM(3)}$	—	$I_{FM} = 3.0\text{ A}$ (pulse measurement)	—	0.49	0.55	
Repetitive peak reverse current	$I_{RRM(1)}$	—	$V_{RRM} = 5\text{ V}$ (pulse measurement)	—	8	—	μA
	$I_{RRM(2)}$	—	$V_{RRM} = 40\text{ V}$ (pulse measurement)	—	17	100	
Junction capacitance	C_j	—	$V_R = 10\text{ V}$, $f = 1.0\text{ MHz}$	—	62	—	pF

7. Marking

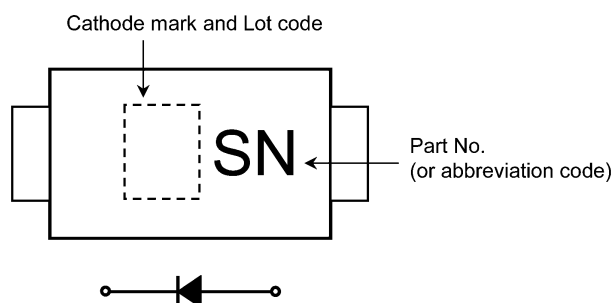


Fig. 7.1 Marking

Marking Code	Part Number
SN	CMS30I40A

8. Usage Considerations

- (1) Schottky barrier diodes (SBDs) have reverse current greater than other types of diodes. This makes SBDs more vulnerable to damage due to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.
- (2) The absolute maximum ratings are rated values that must not be exceeded during operation, even for an instant. The following are the recommended general derating methods for designing a circuit board using this device.
 - V_{RRM} : Use this rating with reference to (1) above. V_{RRM} has a temperature coefficient of 0.1%/°C at low temperatures. Take this coefficient into account when designing a circuit board that will be operated in a low-temperature environment.
 - $I_{F(AV)}$: We recommend that the worst-case current be no greater than 80% of the absolute maximum rating of $I_{F(AV)}$ and that the worst-case junction temperature, T_j , be kept below 120°C. When using this device, allow margins, referring to the $T_{a(max)}-I_{F(AV)}$ curve.
 - I_{FSM} : This rating specifies peak non-repetitive forward surge current. This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.
 - T_j : Derate device parameters in proportion to this rating in order to ensure high reliability. We recommend that the junction temperature (T_j) of a device be kept below 120°C.
- (3) Thermal resistance (junction-to-ambient) varies with the mounting conditions of a device on a circuit board. An appropriate thermal resistance value should be used, considering the heat sink, circuit board design and soldering land size.
- (4) For other design considerations, see the Rectifiers databook or the Toshiba Semiconductor website.

9. Land Pattern Dimensions for Reference Only

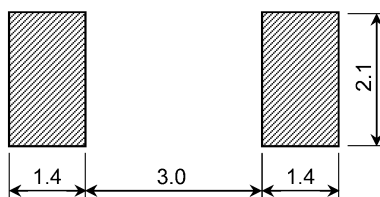
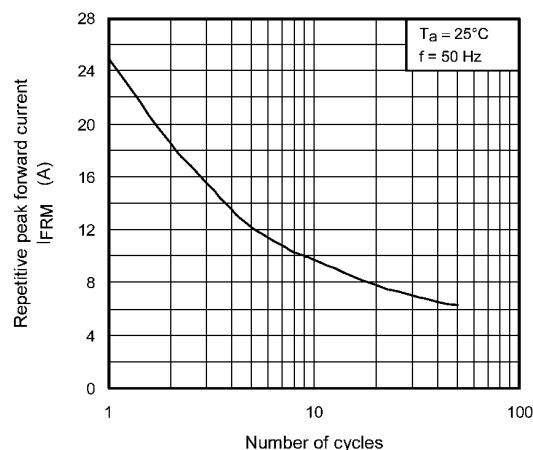
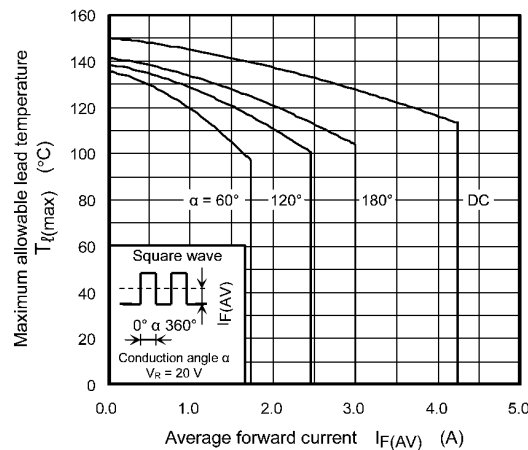
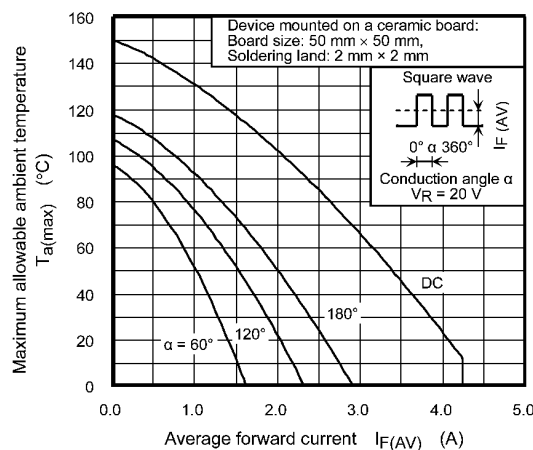
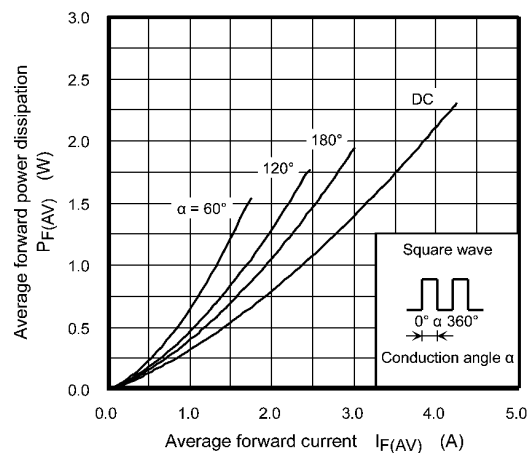
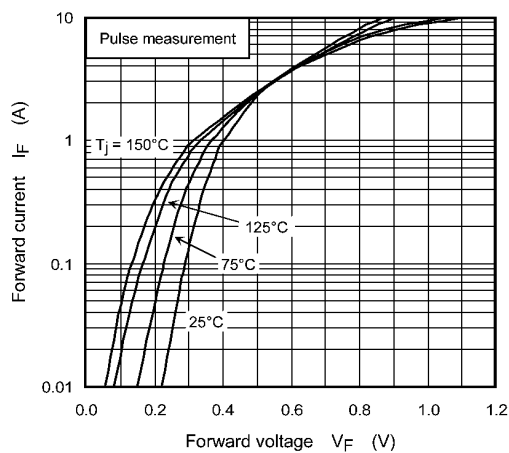


Fig. 9.1 Land Pattern Dimensions for Reference Only (Unit: mm)

10. Characteristics Curves (Note)



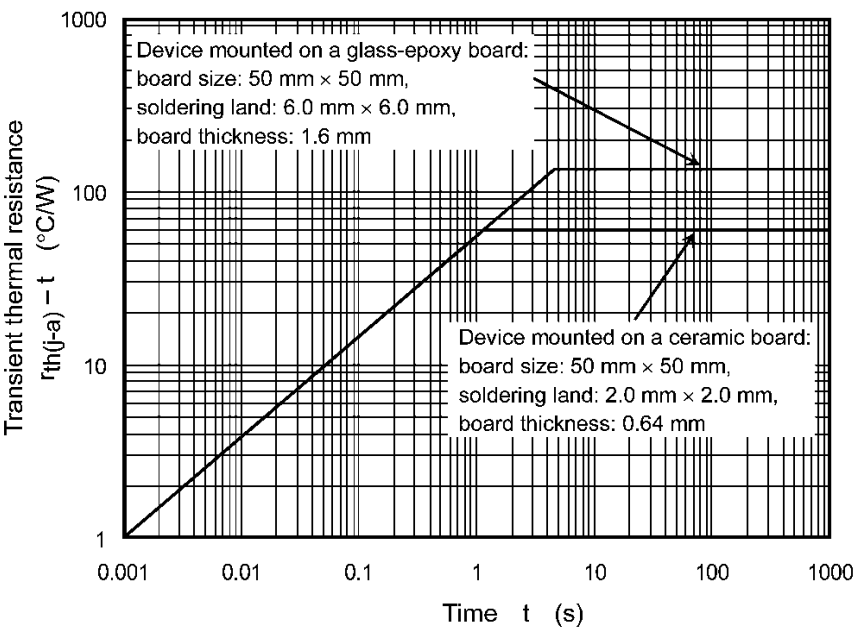


Fig. 10.6 $r_{th(j-a)} - t$

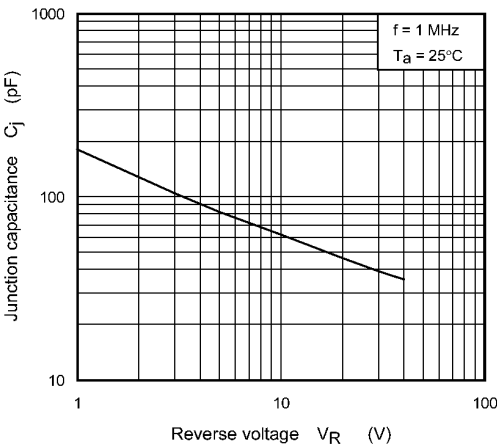


Fig. 10.7 $C_j - V_R$

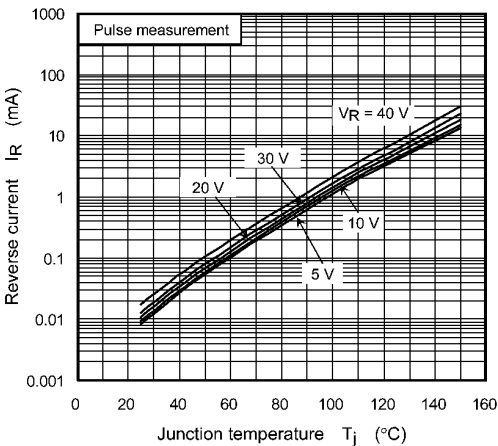
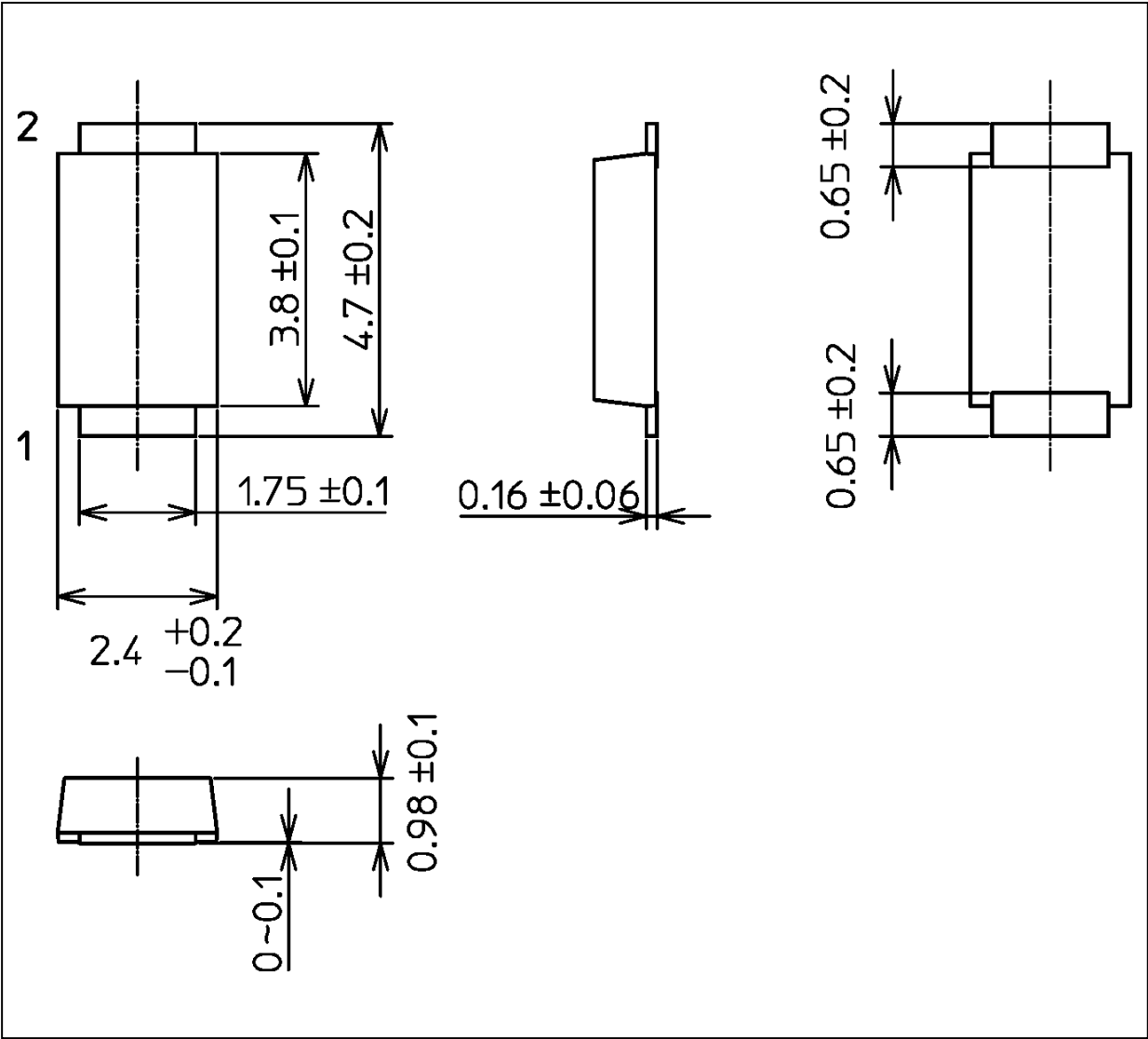


Fig. 10.8 $I_R - T_j$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.023 g (typ.)

Package Name(s)
Nickname: M-FLAT

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